

GP2W3120YP0F

IrDA Compliant Transceiver Module
9.6 kb/s to 4 Mb/s (FIR)
Low Profile
Low Consumption Current



■ Description

The **GP2W3120YP0F** is an infrared transceiver module for IrDA ver. 1.4 (FIR).

The transceiver consists of a pin-photo diode, infrared emitter and control IC in a single package.

This device has remote control transmission function.

■ Features

- Compliant with the IrDA 1.4 (FIR)
Transmission speed : 9.6 kb/s to 4 Mb/s
Transmission distance : 20 cm
- Small package
L 7.16 × W 2.73 × H 1.82 mm
- Peak emission wavelength : 890 nm
(Built-in shared single LED for RC and IrDA)
- Side view type
- Soldering reflow type
- Shield type
- Low consumption current due to shutdown function
(Consumption current at shutdown mode : Max. 1.0 μ A)
- Operates from 2.7 to 3.3 V
- With remote control function
- With LP/HP mode switching function
- With V_{IO} terminal

■ Agency approvals/Compliance

- Compliant with IEC60825-1 class 1 eye safety standard
- Compliant with RoHS directive (2002/95/EC)
- Content status of six substances specified in “Management Methods for Control of Pollution Caused by Electronic Information Products Regulation” (popular name : *China RoHS*) (Chinese : 电子信息产品污染控制管理办法)**
; refer to page 14
- Lead (Pb) free device

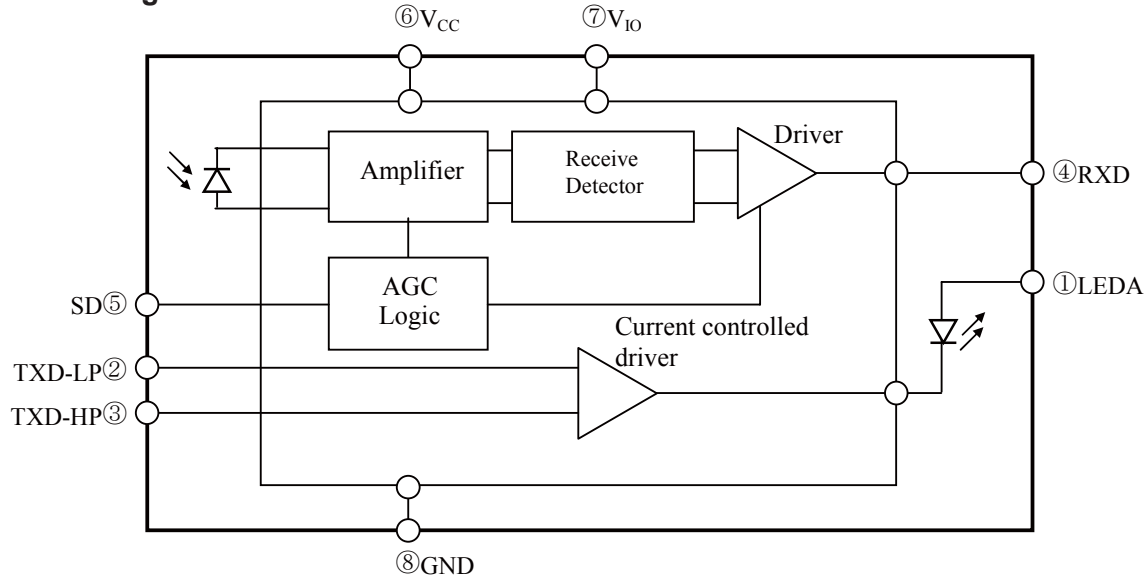
■ Applications

- Mobile equipment
(Cellular phone, Pager, Smart phone, PDAs, Portable printer, etc.)
- Digital imaging equipment
(Digital camera, Photo imaging printer)
- POS equipment
- Personal computers
- Personal information tools

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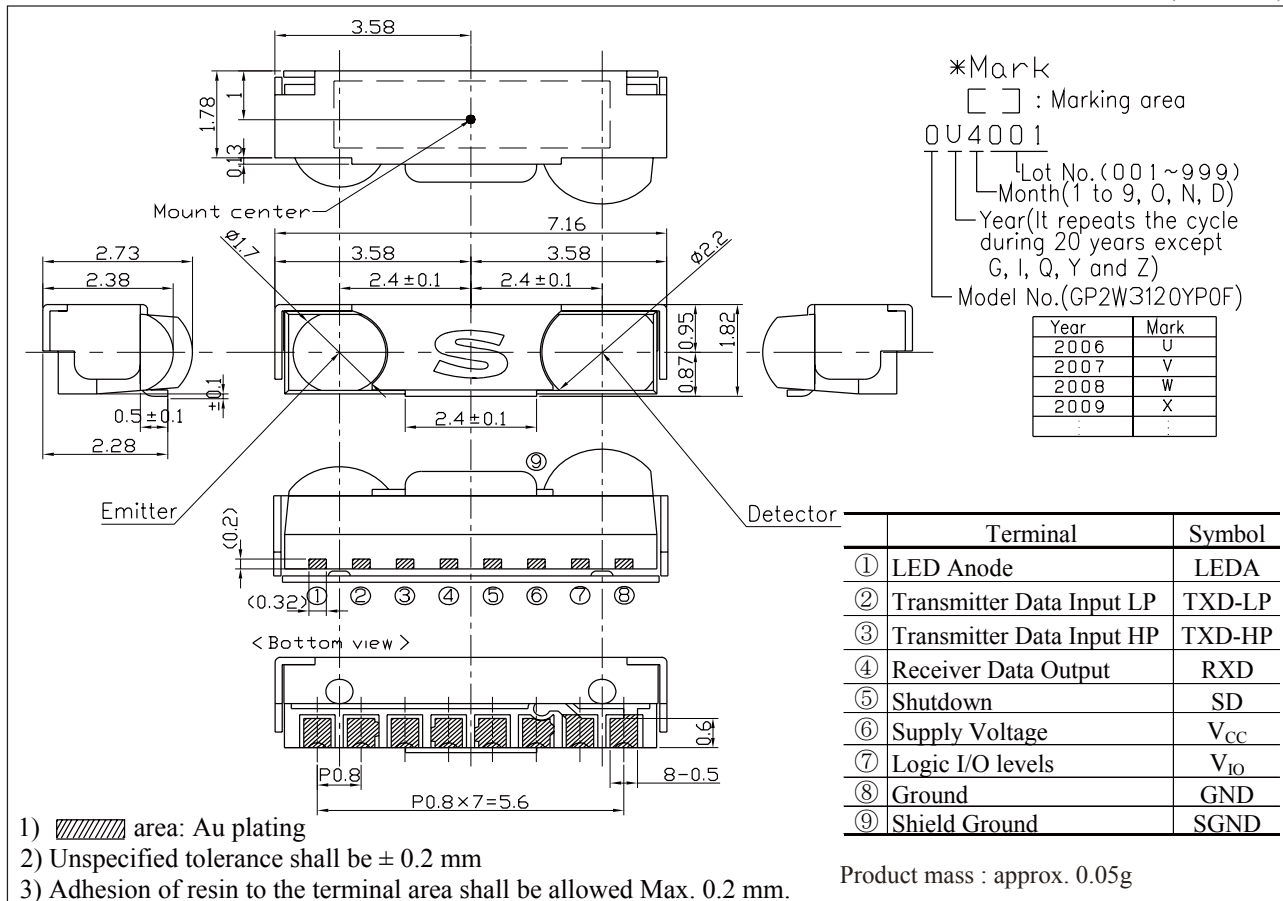
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■ Block diagram



■ Outline Dimensions

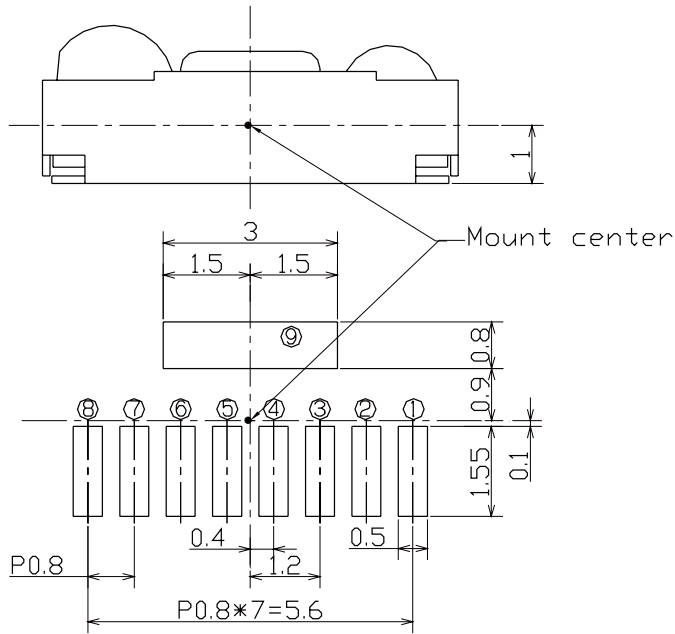
(Unit : mm)



Recommended PCB Foot Pattern

Dimensions are shown for reference

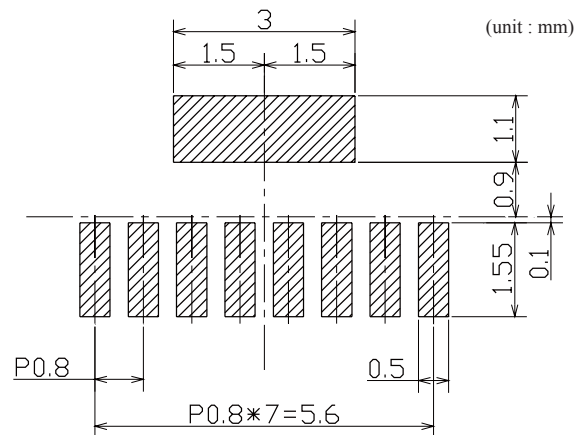
(Unit:mm)



	Terminal	Symbol
①	LED Anode	LEDA
②	Transmitter Data Input LP	TXD-LP
③	Transmitter Data Input HP	TXD-HP
④	Receiver Data Output	RXD
⑤	Shutdown	SD
⑥	Supply Voltage	V _{CC}
⑦	Logic I/O levels	V _{IO}
⑧	Ground	GND
⑨	Shield Ground	SGND

Recommended Size of Solder Creamed Paste (Reference)

Dimensions are shown for reference.
Please open the solder mask as below so that the size of solder creamed paste for this device before reflow soldering must be as large as one of the foot pattern land indicated for reference.



: Solder paste area

■ Absolute Maximum Ratings (T_a=25°C)

Parameter	Symbol	Rating	Unit
Supply voltage	V _{CC}	-0.3 to 6.0	V
LED Supply voltage	V _{LED}	-0.3 to 3.6	V
Transmission Data Input LP	TXD-LP	-0.3 to V _{CC} +0.3	V
Transmission Data Input HP	TXD-HP	-0.3 to V _{CC} +0.3	V
Shut down	SD	-0.3 to V _{CC} +0.3	V
Logic I/O levels	V _{IO}	-0.3 to V _{CC} +0.3	V
*1 Peak forward current	I _{FM}	330	mA
Operating temperature	T _{opr}	-25 to +85	°C
Storage temperature	T _{stg}	-40 to +85	°C
*2 Soldering temperature	T _{sol}	260	°C

*1 Pulse operation (FIR 4 Mb/s)

*2 Soldering reflow time : 10 seconds

Electro-optical Characteristics

(T_{opt}=25±5°C, V_{CC}=3.0V Unless otherwise specified)

Parameter		Symbol	Rating	MIN.	TYP.	MAX.	Unit
Current consumption at no input signal	SIR mode	I _{CC-SIR}	No input signal, V _{ILSD} =0V	—	0.45	0.6	mA
	FIR mode	I _{CC-FIR}	Output terminal OPEN	—	1.2	1.55	mA
Current consumption at receiving	SIR mode	I _{CC-RSIR}	V _{ILSD} =0V	—	0.65	—	mA
	FIR mode	I _{CC-RFIR}	Output terminal OPEN	—	1.3	—	mA
Current consumption at Transmitting	All mode	I _{CC-T}	V _{IHTXD-LP} =High or, V _{IHTXD-HP} =High, V _{ILSD} =0V	—	27	55	mA
Current consumption at Shutdown mode		I _{CC-S}	No input signal, V _{IHSD} =V _{CC} -1.2V Output terminal OPEN	—	0.01	1.0	μA
Receiver	High level output voltage	V _{OH}	I _{OH} =0.3mA ^{*3}	V _{IO} -0.5	V _{IO} -0.3	V _{IO} +0.3	V
	Low level output voltage	V _{OL}	I _{OL} =1mA ^{*3}	—	—	0.6	V
	Rise time	t _r	BR=4Mb/s, C _L =15pF, T _a =25°C ^{*5}	—	—	50	ns
	Fall time	t _f		—	—	50	ns
	Low level pulse width	t _{w1}	t _{w1} , E _{e1} ; BR=9.6kb/s, φ ≤ 15° t _{w2} , E _{e1} ; BR=115.2kb/s, φ ≤ 15° t _{w3} , E _{e2} ; BR=4Mb/s(single), φ ≤ 15° t _{w4} , E _{e2} ; BR=4Mb/s(double), φ ≤ 15° T _a =25°C	1	—	24	μs
		t _{w2}		1	—	4	μs
		t _{w3}		67	—	195	ns
		t _{w4}		190	—	320	ns
	Maximum reception distance	L		21	—	—	cm
	Input irradiance	E _{e1}	Except for pulse during a half of preamble	—	—	8.16	μW/cm ²
		E _{e2}		—	—	20.4	μW/cm ²
	Overload irradiance	E _{e3}		500	—	—	mW/cm ²
	Receiver Latency	t _l		—	—	500	μs
	Receiver wakeup time	t _{sdw}	No input signal	—	—	1	ms
	SD input current	I _{isd}	V _{IHSD} =V _{CC} , V _{ILSD} =GND	-0.1	0	+0.1	μA
	SD terminal Input voltage Logic High	V _{IHSD}	Shutdown mode	V _{CC} -1.2	—	V _{CC}	V
SD terminal Input voltage Logic Low	V _{ILSD}	Normal mode	—	—	0.5	V	
Jitter	t _j	BR=4Mb/s, T _a =25°C	—	30	60	ns	
Radiant intensity	Low power	I _{E-LP}	V _{LED} =3.3V, R _{LED} =4.3Ω φ ≤ 15°, T _a =25°C ^{*4}	10	—	—	mW/sr
	High power	I _{E-HP}	V _{LED} =3.3V, R _{LED} =4.3Ω φ =15°, T _a =25°C ^{*4}	25	—	—	mW/sr
LED peak current	Low power	I _{LED-LP}	V _{LED} =3.3V, R _{LED} =4.3Ω, T _a =25°C ^{*4}	100	150	200	mA
	High power	I _{LED-HP}		150	250	330	mA
Rise time	t _r	BR=4Mb/s, V _{LED} =3.3V, T _a =25°C ^{*4}	—	—	40	ns	
Fall time	t _f		—	—	40	ns	
Peak emission wave length	λ _p	T _a =25°C	870	890	900	nm	
TXD-LP / TXD-HP high level input voltage	V _{IHTXD}	LED(ON), 1.5 ≤ V _{IO} ≤ 1.8V	1.4	—	V _{CC}	V	
		LED(ON), 1.8 < V _{IO} ≤ V _{CC}	1.6	—	V _{CC}	V	
TXD-LP / TXD-HP low level input voltage	V _{ILTXD}	LED(OFF)	—	—	0.6	V	
TXD-LP TXD-HP high level input current	I _{IHTXD}	T _a =25°C	—	—	20	μA	
TXD-LP TXD-HP low level input current	I _{ILTXD}	T _a =25°C	—	—	8	μA	
Maximum optical pulse width	t _{OPWM}	TXD pin stuck high	30	—	300	μs	

*3 Refer to Fig. 2, 3

*4 Refer to Fig. 4,5,6

Recommended Operating Conditions

($T_a=25^\circ\text{C}$)

Parameter	Symbol	Conditions	Rating	Unit
Supply voltage	V_{CC}		2.7 to 3.3	V
LED Supply voltage	V_{LED}	$R_{LED}=4.3\Omega$	2.7 to 3.6	V
Operating temperature	T_{opr}	*5	-25 to +85	$^\circ\text{C}$
Data rate	BR		9.6k to 4M	b/s
Logic I/O levels	V_{IO}		1.5 to V_{CC}	V

*5 When you make Duty 25 % of signal emit light continuously, please use continuation luminescence time in less than 10 seconds.

Truth Table

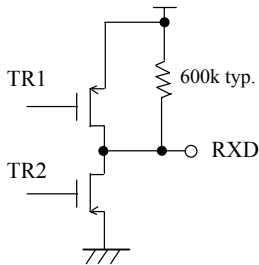
MODE	SD	SW	TXD-LP	TXD-HP	LED	Receiver	TR1	TR2	RXD
Shutdown	H	Off	L	L	Off	Don't Care	Off	Off	H(Pull-up)
Transmitter	LP	On	H	L	LP	Don't Care	Off	On	L(echo)
	HP	On	L	H	HP	Don't Care	Off	On	L(echo)
Receiver	L	On	L	L	Off	IrDA Signal	Off	On	L
	L	On	L	L	Off	No Signal	On	Off	H

H:high, L:Low

LP : Low power IE, HP : High power IE

(Note) Don't input Transmitter LP high signal and HP high signal at the same time in transmitter mode.

*RXD equivalent circuit



*TXD equivalent circuit

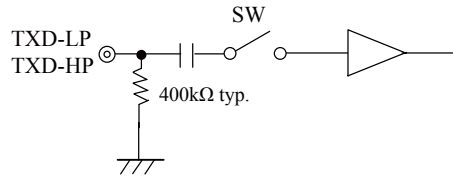
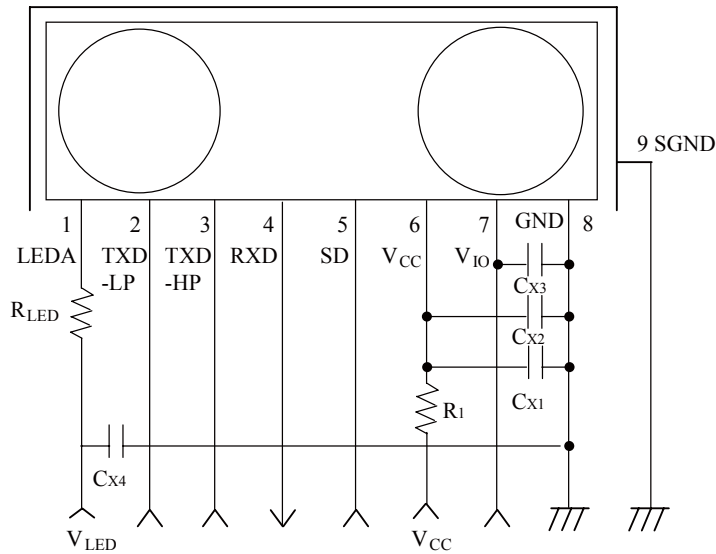


Fig.1 Recommended External Circuit



Components	Recommended values	
C _{X1}	4.7μF(Ceramic)(Note1)	
C _{X2}	0.47μF(Ceramic)(Note1)	
C _{X3}	0.47μF(Ceramic)(Note1)	
C _{X4}	10μF(Ceramic)(Note1)	
R ₁ (1/16W)	4.7Ω	
R _{LED}	1/4W	4.3Ω(V _{LED} =3.3V)
	(Note2) 1/10W	2.4Ω(V _{LED} =2.85V)

(Note1) Components choose the most suitable C_{X1}, C_{X2}, C_{X3}, C_{X4} according to the noise level and noise frequency of power supply.

(Note2) In order to guarantee (10 mW/sr), V_{LED} is required 3.3 V (R_{LED} = 4.3 Ω), V_{LED} is required 2.85 V (R_{LED} = 2.4 Ω).

Fig.2 Output Waveform Specification(Receiver side)

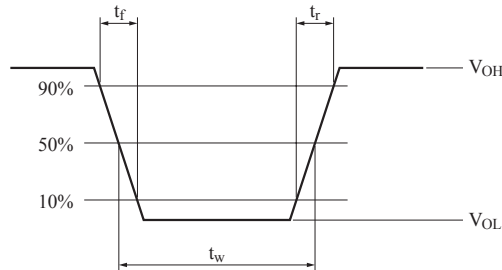
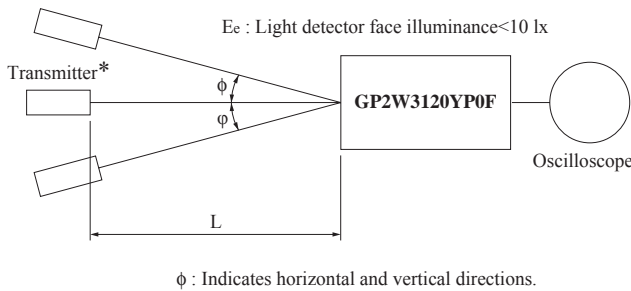


Fig.3 Standard Optical System(Receiver side)



Data rate	T_1	T_2	T_2/T_1	Radiant intensity
9.6kb/s	103 μ s	19.5 μ s	3/16	3.6mW/sr
115.2kb/s	8.68 μ s	1.63 μ s	3/16	40mW/sr
4Mb/s	500ns	125ns	1/4	9mW/sr
4Mb/s	500ns	250ns	1/2	9mW/sr

* Transmitter shall use the standard transmitter ($\lambda_p = 890$ nm TYP.) which is adjusted the radiation intensity at 3.6 mW/sr (at 9.6 to 115.2 kb/s), 9 mW/sr (at 4 Mb/s).

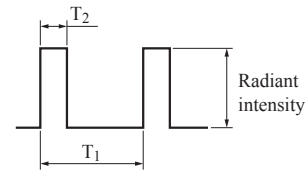


Fig.4 Output Waveform Specification(Transmitter side)

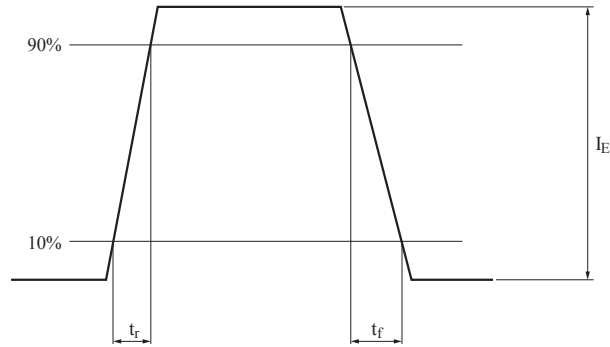


Fig.5 Standard Optical System(Transmitter side)

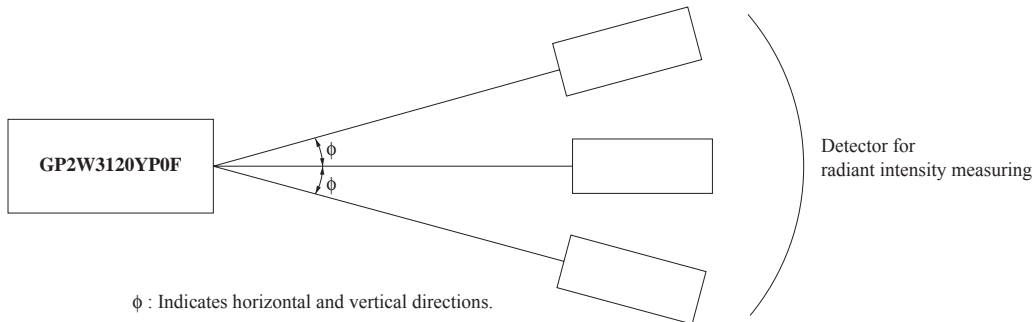


Fig.6 Recommended Circuit of Transmitter side

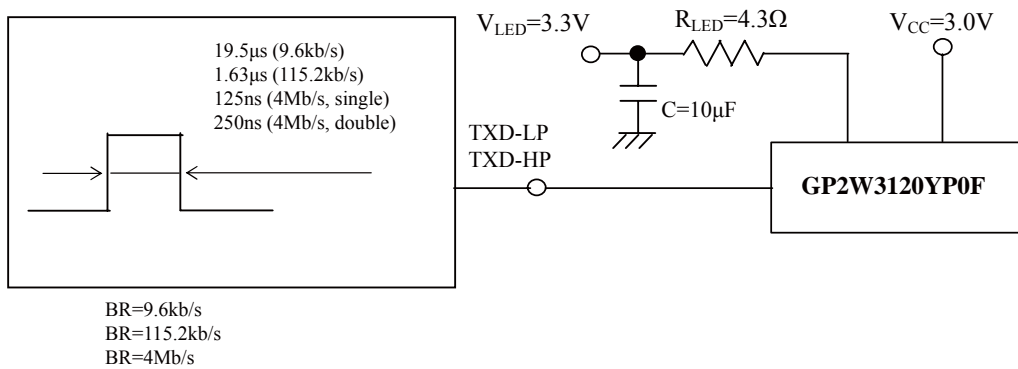
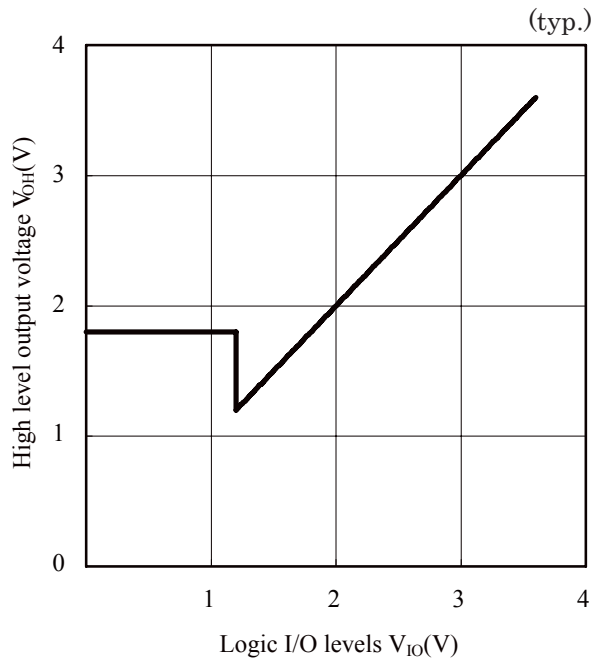


Fig.7 High level output voltage(V_{OH}) vs Logic I/O levels(V_{IO})

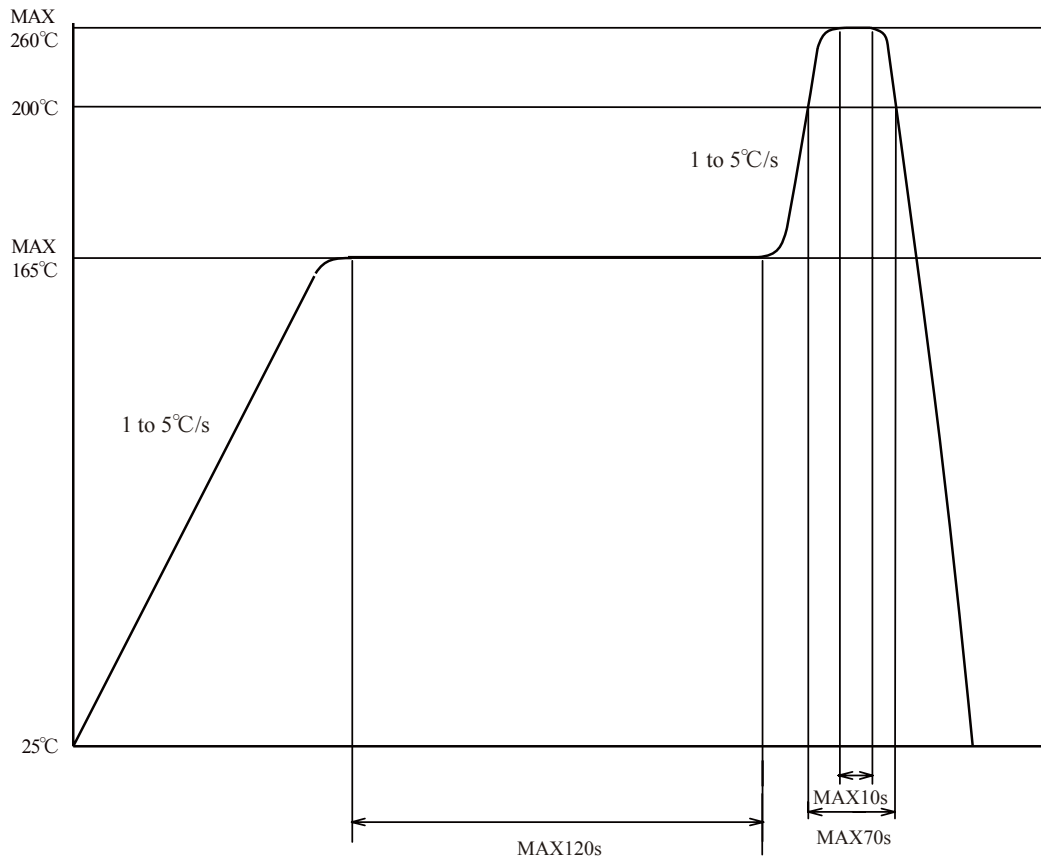
■ Notes

- (1) When the system (program) is designed, the Turn Around Time shall be secured by considering 500 μ s or more that is specified to IrDA.
Then, this Turn Around Time means the time when this device does not temporarily detect the signal light, since the transmitted light from the transceiver reaches the detector side of the transceiver.
- (2) As it is necessary 1 ms or more (at $T_a = 25$ °C, no input signal) to return from shut-down mode to ready-operation mode, please consider this point at the system (program) designing.
Also, please confirm thoroughly the operation in actual application.
- (3) When there is much external disturbing light source is located near this transceiver and the detector face receiver much external disturbing light, there is case that the pulse other than signal output is generated as noise on output terminal of this transceiver. Please consider the lay-out and structure to reduce disturbing light on the detector face.
- (4) In case that this sensor is adopted in IR communication system, please use it according to the signal method which is specified by [Serial Infrared Physical Layer Link Specification Version 1.4] published by Infrared Data Association. False operation may happen if the different signal method is used.
- (5) In circuit designing, make allowance for the degradation of light emitting diode output that results from long continuous operation. (50 % degradation/5 years)

■ Soldering Method

1. In case of solder reflow

Please carry out only two times soldering at the temperature and the time within the temperature profile as shown in the figure below. Reflow interval shall be within 3 days under conditions, 10 to 30°C, 70%RH or less.



2. Other precautions

An infrared lamp used to heat up for soldering may cause a localized temperature rise in the resin. So keep the package temperature within that specified in Item 1. Also avoid immersing the resin part in the solder. Even if within the temperature profile above, there is the possibility that the gold wire in package is broken in case that the deformation of PCB gives the affection to lead pins. Please use after confirming the conditions fully by actual solder reflow machine.

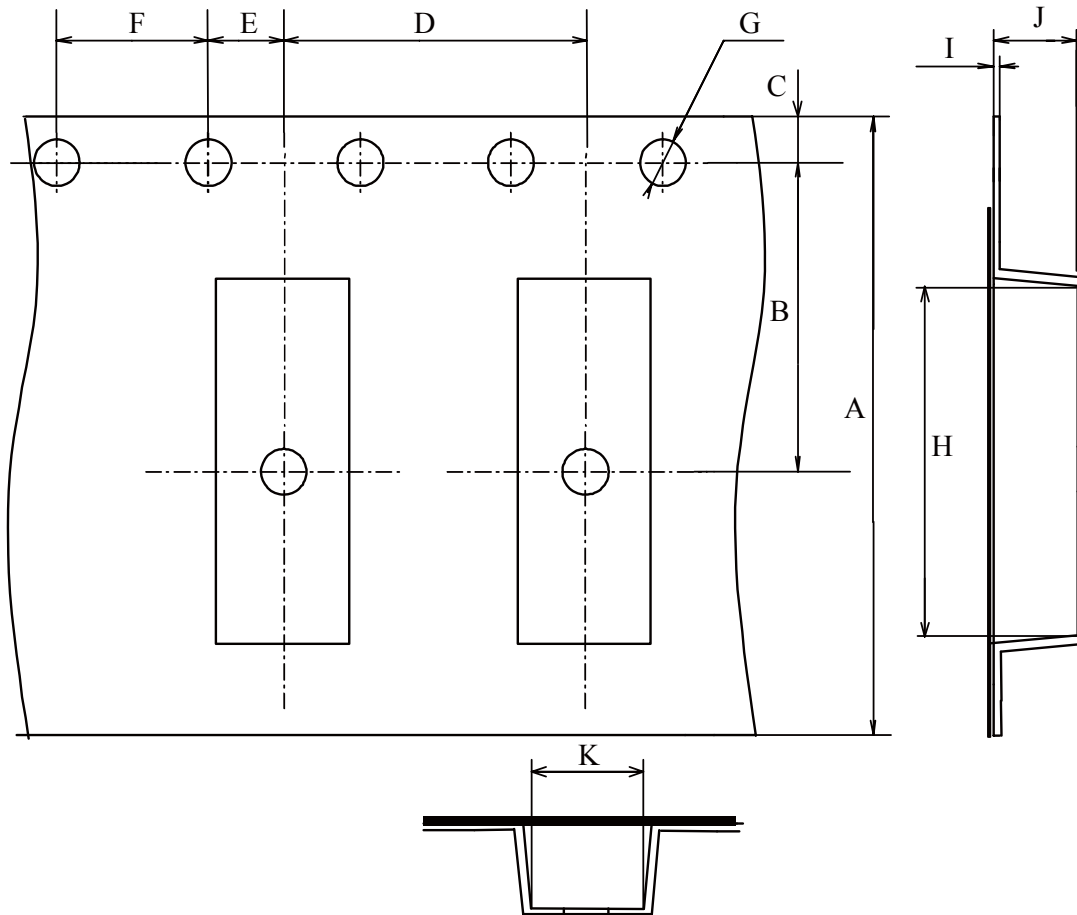
3. Soldering

- Soldering iron shall be less than 25W, and temperature of point of soldering iron shall use at 300°C or less.
- Soldering time shall be within 5s.
- Soldered product shall treat at normal temperature.

■ Package specification

- Tape and Reel package
- 2000 pcs/reel

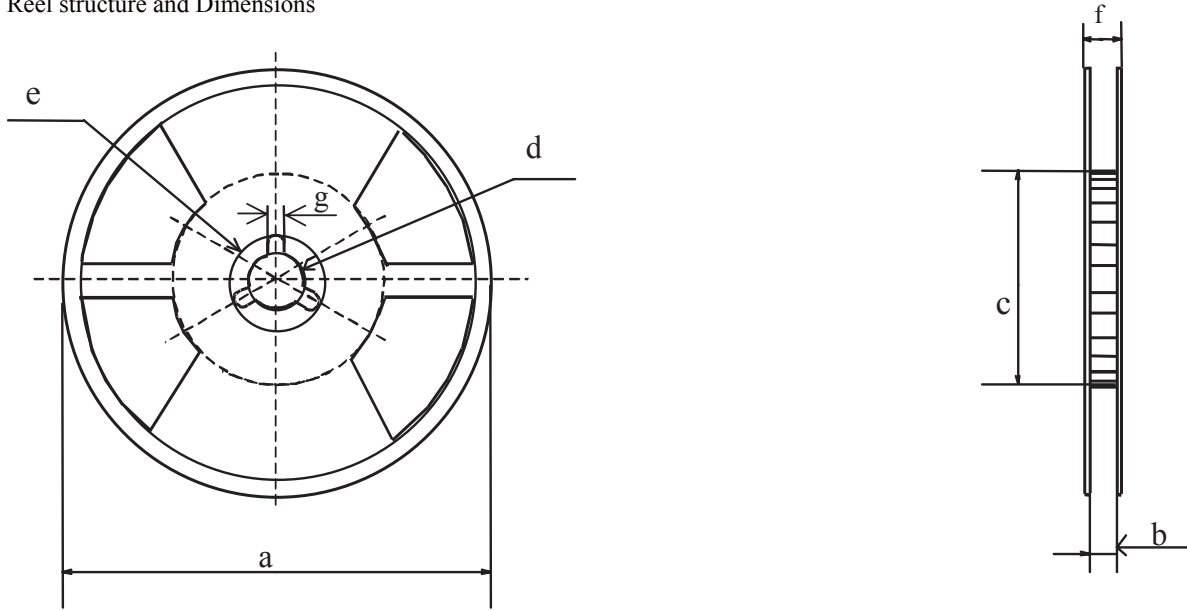
Carrier tape structure and Dimensions



(Unit : mm)

A	B	C	D	E	F
16.0±0.3	7.5±0.1	1.75±0.1	8.0±0.1	2.0±0.1	4.0±0.1
G	H	I	J	K	
$\phi 1.5^{+0.1}_{-0.0}$	7.45±0.1	0.32±0.05	2.1±0.1	2.8±0.1	

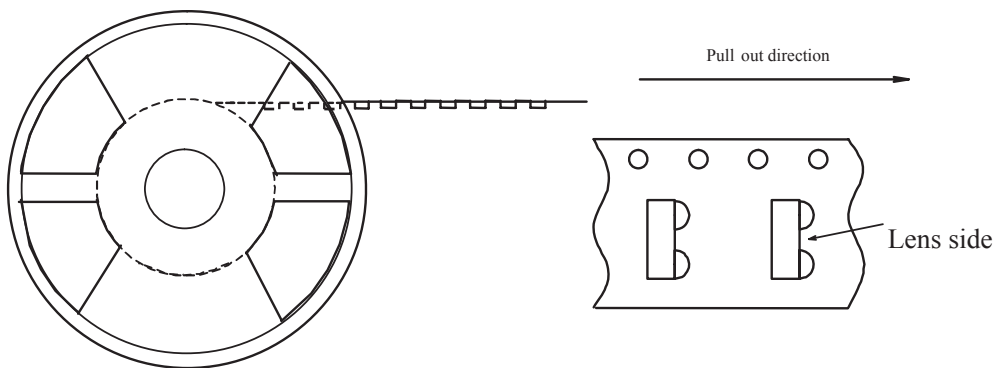
Reel structure and Dimensions



Dimension List (Unit : mm)

a	b	c	d
$\phi 330 \pm 2$	17.5 ± 1.0	$\phi 100 \pm 1$	$\phi 13 \pm 0.2$
e	f	g	
$\phi 21 \pm 0.8$	22.4 ± 1.0	2 ± 0.5	

Direction of product insertion



● **Cleaning Instructions**

Solvent cleaning :

Solvent temperature 45°C or less, Immersion for 3 min or less

Ultrasonic cleaning :

The effect to device by ultrasonic cleaning differs by cleaning bath size, ultrasonic power output, cleaning time, PCB size or device mounting condition etc.

Please test it in actual using condition and confirm that doesn't occur any defect before starting the ultrasonic cleaning. The cleaning shall be carried out with solvent below.

Recommended Solvent materials :

Ethyl alcohol, Methyl alcohol, Isopropyl alcohol

● **Presence of ODC etc.**

This product shall not contain the following materials.

And they are not used in the production process for this product.

Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBB and PBDE are not used in this product at all.

• **The RoHS directive (2002/95/EC)**

This product complies with the RoHS directive (2002/95/EC).

Object substances: lead, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE)

• **Content of six substances specified in “ Management Methods for Control of Pollution Caused by Electronic Information Products Regulation ” (Chinese : 电子信息产品污染控制管理办法)**

Category	Toxic and hazardous substances					
	Lead (Pb)	Mercury (Hg)	Cadmium (Cd)	Hexavalent chromium (Cr ⁶⁺)	Polybrominated biphenyls (PBB)	Polybrominated diphenyl ethers (PBDE)
Infrared data communication device	✓	✓	✓	✓	✓	✓

✓ : indicates that the content of the toxic and hazardous substance in all the homogeneous materials of the part is below the concentration limit requirement as described in SJ/T 11363-2006 standard.

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- Personal computers
- Office automation equipment
- Telecommunication equipment [terminal]
- Test and measurement equipment
- Industrial control
- Audio visual equipment
- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection

with equipment that requires higher reliability such as:

- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
- Traffic signals
- Gas leakage sensor breakers
- Alarm equipment
- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:

- Space applications
- Telecommunication equipment [trunk lines]
- Nuclear power control equipment
- Medical and other life support equipment (e.g., scuba).

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